

SOT122E

studded ceramic package; 4 leads

8 February 2016

Package information

1. Package summary

| | |
|--------------------------------|---|
| Terminal position code | R (radial) |
| Package type descriptive code | CRPM4 |
| Package type industry code | CRPM4 |
| Package style descriptive code | CRPM (ceramic radial post (stud) mount) |
| Package style suffix code | NA (not applicable) |
| Package body material type | C (ceramic) |
| Mounting method type | S (surface mount) |
| Issue date | 29-3-1999 |

Table 1. Package summary

| Symbol | Parameter | | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|--|------|-----|-------|------|------|
| D | package length | | 7.23 | - | 7.365 | 7.5 | mm |
| A | seated height | | 4.8 | - | 5.385 | 5.97 | mm |
| n ₂ | actual quantity of termination | | - | - | 4 | - | |



2. Package outline

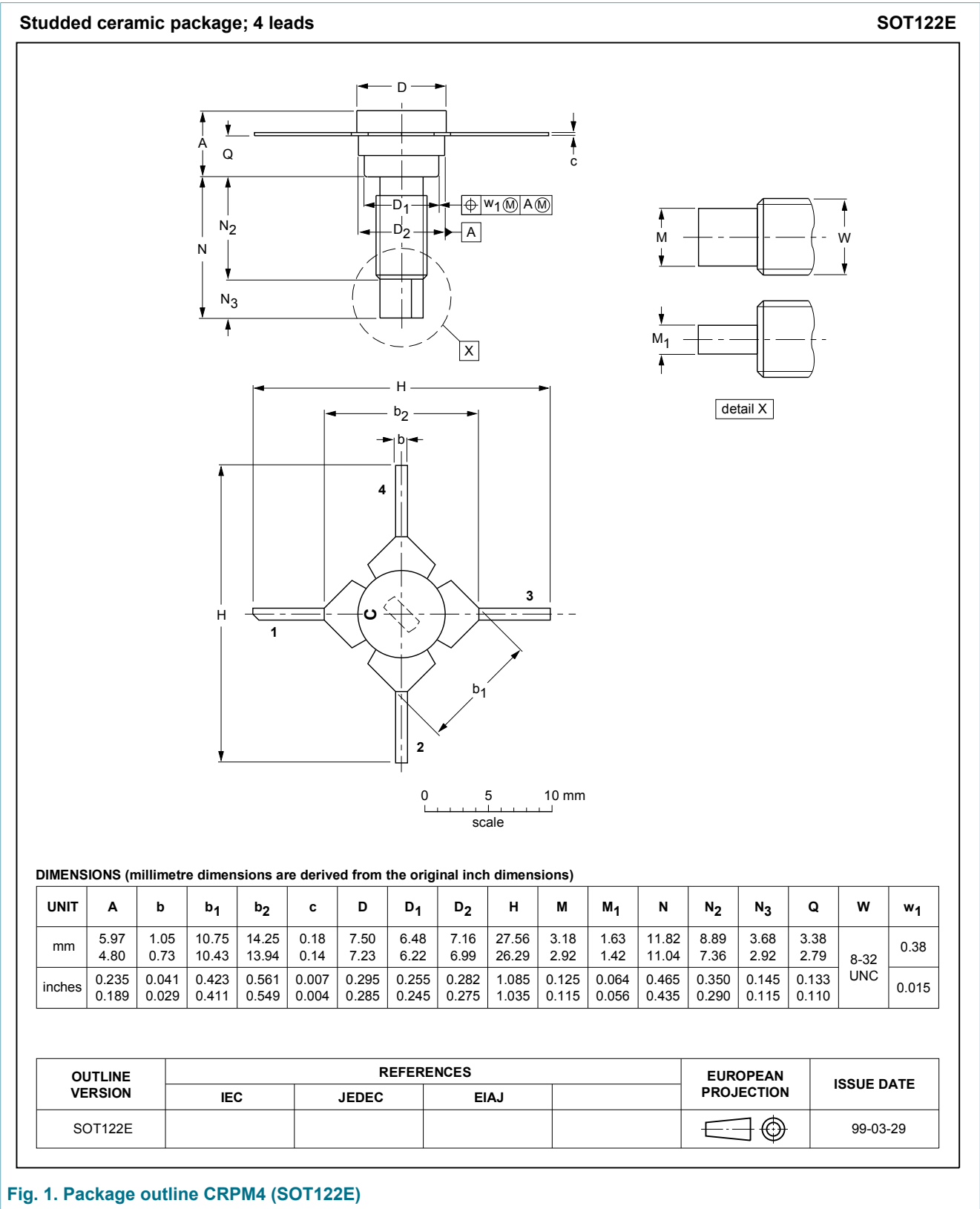


Fig. 1. Package outline CRPM4 (SOT122E)

3. Legal information

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